

6-OUTPUT LOW POWER DIFFERENTIAL SYNTHESIZER FOR PCIE GEN2

9FGL699

Description

The 9FGL699 is a 6-output low-power clock sythesizer for PCIe Gen2. It runs from a 25MHz XTAL, provides spread spectrum capability, and has an SMBus for software control of the device.

Recommended Application

6-Output Low Power Differential Synthesizer for PCle Gen2

Output Features

6 - 100MHz Differential low power push pull (HCSL compatible) output pairs

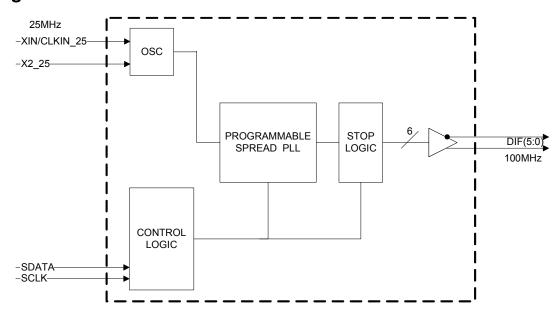
Features/Benefits

- 32-pin QFN; Space-savings
- Push Pull outputs; Low power consumption, reduced component count
- PCle Gen2; Supports latest systems
- Spread Spectrum Capability; reduced EMI when needed
- D2/D3 SMBus Write/Read SMBus address

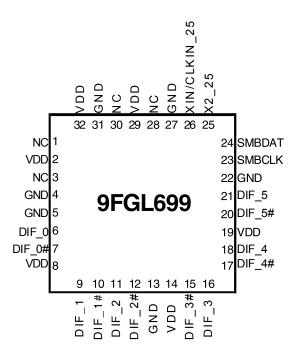
Key Specifications

- Cycle-to-cycle jitter < 85ps
- Output-to-output skew < 100 ps
- Current consumption < 40mA
- PCIe Gen2 phase jitter < 3.0ps RMS

Block Diagram







Power Management

OE (SMBUS)	Differential Outputs
1	DIF/DIF# = running
0	DIF/DIF# = Low/Low



Pin#	Pin Name	Type	Pin Description
1	NC NC	N/A	No Connection.
-			
2	VDD		Power supply, nominal 3.3V
3	NC	N/A	No Connection.
4	GND	PWR	Ground pin.
5	GND		Ground pin.
6	DIF_0		0.7V differential true clock output
7	DIF_0#		0.7V differential Complementary clock output
8	VDD		Power supply, nominal 3.3V
9	DIF_1		0.7V differential true clock output
10	DIF_1#	OUT	0.7V differential Complementary clock output
11	DIF_2	OUT	0.7V differential true clock output
12	DIF_2#	OUT	0.7V differential Complementary clock output
13	GND	PWR	Ground pin.
14	VDD	PWR	Power supply, nominal 3.3V
15	DIF_3#	OUT	0.7V differential Complementary clock output
16	DIF_3	OUT	0.7V differential true clock output
17	DIF_4#	OUT	0.7V differential Complementary clock output
18	DIF_4	OUT	0.7V differential true clock output
19	VDD	PWR	Power supply, nominal 3.3V
20	DIF 5#	OUT	0.7V differential Complementary clock output
21	DIF_5	OUT	0.7V differential true clock output
22	GND	PWR	Ground pin.
23	SMBCLK	IN	Clock pin of SMBUS circuitry, 5V tolerant
24	SMBDAT	I/O	Data pin of SMBUS circuitry, 5V tolerant
25	X2 25	OUT	Crystal output, Nominally 25.00MHz.
26	XIN/CLKIN_25	IN	Crystal input or Reference Clock input. Nominally 25MHz.
27	GND	PWR	Ground pin.
28	NC	N/A	No Connection.
29	VDD		Power supply, nominal 3.3V
30	NC	N/A	No Connection.
31	GND		Ground pin.
32	VDD		Power supply, nominal 3.3V



How to Write

- · Controller (host) sends a start bit
- · Controller (host) sends the write address
- IDT clock will acknowledge
- Controller (host) sends the beginning byte location = N
- IDT clock will acknowledge
- Controller (host) sends the byte count = X
- IDT clock will acknowledge
- Controller (host) starts sending Byte N through Byte N+X-1
- IDT clock will acknowledge each byte one at a time
- · Controller (host) sends a Stop bit

	Index Block Write Operation								
Controll	er (Host)		IDT (Slave/Receiver)						
Т	starT bit								
Slave A	Address								
WR	WRite								
			ACK						
Beginning	g Byte = N								
			ACK						
Data Byte	Count = X								
			ACK						
Beginnin	g Byte N								
			ACK						
0		\perp							
0		X Byte	0						
0		Ö	0						
			0						
Byte N	+ X - 1								
			ACK						
Р	stoP bit								

Read Address	Write Address
D3 _(H)	D2 _(H)

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How to Read

- · Controller (host) will send a start bit
- Controller (host) sends the write address
- IDT clock will acknowledge
- Controller (host) sends the beginning byte location = N
- IDT clock will acknowledge
- Controller (host) will send a separate start bit
- · Controller (host) sends the read address
- IDT clock will acknowledge
- IDT clock will send the data byte count = X
- IDT clock sends Byte N+X-1
- IDT clock sends Byte 0 through Byte X (if X_(H) was written to Byte 8)
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- · Controller (host) will send a stop bit

	Index Block F	Read O	peration
Cor	troller (Host)		IDT (Slave/Receiver)
Т	starT bit		
SI	ave Address		
WR	WRite		
			ACK
Begi	nning Byte = N		
			ACK
RT	Repeat starT		
SI	ave Address		
RD	ReaD		
			ACK
			Data Byte Count=X
	ACK		
			Beginning Byte N
	ACK		
		<u>e</u>	0
	0	X Byte	0
	0	×	0
	0		
			Byte N + X - 1
N	Not acknowledge		
Р	stoP bit		

9FGL699



SMBus Table: Device Control Register, READ/WRITE ADDRESS (D3/D2)

Byt	te 0	Pin #	Name	Control Function	Type	0	1	Default
Bit 7		-		Reserv	ed			0
Bit 6		- Reserved						0
Bit 5			Spre	ead Enable	RW	Off	-0.50%	1
Bit 4		- Reserved				0		
Bit 3		-		Reserv	ed			0
Bit 2		- Reserved					0	
Bit 1	- P					0		
Bit 0		-		Reserv	ed			0

SMBus Table: Output Enable Register

Byt	te 1	Pin #	Name	Control Function	Type	0	1	Default	
Bit 7		-		Reserved					
Bit 6		-	DIF_0 EN	Output Enable	RW	Disable	Enable	1	
Bit 5		-		Reserv	ed			0	
Bit 4		-		Reserv	ed			0	
Bit 3		-	DIF_1 EN	Output Enable	RW	Disable	Enable	1	
Bit 2		-		Reserv	ed			0	
Bit 1		-		Reserved					
Bit 0		-		Reserv	ed			0	

SMBus Table: Reserved Register

			o a rito grotor						
Ву	te 2	Pin #	Name	Control Function	Type	0	1	Default	
Bit 7		-		Reserved					
Bit 6		- Reserved						0	
Bit 5	- Reserved					0			
Bit 4		-		Reserv	ed			0	
Bit 3		-		Reserv	ed			0	
Bit 2		- Reserved						0	
Bit 1		-	Reserved					0	
Bit 0		-		Reserv	ed			0	

SMBus Table: Output Enable Register

Byte	e 3	Pin #	Name	Control Function	Type	0	1	Default
Bit 7		-	DIF_5 EN	Output Enable	RW	Disable	Enable	1
Bit 6		-	DIF_4 EN	Output Enable	RW	Disable	Enable	1
Bit 5	- Reserved					0		
Bit 4		-		Reserv	ed			0
Bit 3		-		Reserv	ed			0
Bit 2		- Reserved				0		
Bit 1		- Reserved				0		
Bit 0		-		Reserv	ed			0



SMBus Table: Reserved Register

Byt	e 4	Pin#	Name	Control Function	Type	0	1	Default
Bit 7		-		Reserv	ed			0
Bit 6		- Reserved						
Bit 5		- Reserved						0
Bit 4		-		Reserved				
Bit 3		-		Reserv	ed			0
Bit 2		-	Reserved					
Bit 1		-	Reserved					
Bit 0		-		Reserv	ed			0

SMBus Table: Output amplitude adjustment

Byt	te 5	Pin#	Name	Control Function	Type	0	1	Default
Bit 7		-	DIF 5/6 AMP	Amplitude adjustment	RW	00=700mV 01=800mV 10=900mV 11=1000mV		0
Bit 6		-	DII _5/6 AIVIF	Amplitude adjustment	RW			1
Bit 5		-	DIF 1/2/3 AMP	Amplitude adjustment	RW		00=700mV 01=800mV 10=900mV 11=1000mV	
Bit 4		-	DII _ 1/2/3 AIVII	Ampiliade adjustment	RW			
Bit 3		-		Reserv	ed			0
Bit 2		-		Reserv	ed			0
Bit 1		-	DIF 0 AMP	Amplitude adjustment	RW		00mV 00mV	0
Bit 0		-	Dii _0 Alvii	Ampiliade adjustinent	RW		00mV 000mV	1

SMBus Table: Reserved Register

Byt	Byte 6 Pin #		Name	Control Function	Type	0	1	Default	
Bit 7		-	Reserved						
Bit 6		- Reserved							
Bit 5		-		Reserv	ed			0	
Bit 4		-		Reserv	ed			0	
Bit 3		-		Reserv	ed			0	
Bit 2		-		Reserved					
Bit 1		-		Reserved					
Bit 0		-		Reserv	ed			0	

SMBus Table: Vendor & Revision ID Register

Byt	:e 7	Pin#	Name	Control Function	Type	0	1	Default
Bit 7	-	'	RID3		R	-	-	0
Bit 6	-	'	RID2	REVISION ID	R	-	-	0
Bit 5	-		RID1	REVISION ID	R	-	-	0
Bit 4	-		RID0		R	-	-	0
Bit 3	-		VID3		R	-	-	0
Bit 2	-	,	VID2	VENDOR ID	R	-	-	0
Bit 1	-		VID1	VENDOR ID	R	-	-	0
Bit 0	-		VID0		R	-	-	1



SMBus Table: Reserved Register

Byt	te 8	Pin#	Name	Name Control Function Type 0		1	Default			
Bit 7				Reserv	ed			0		
Bit 6				Reserved						
Bit 5				Reserved						
Bit 4				Reserved						
Bit 3				Reserv	ed			1		
Bit 2				Reserved						
Bit 1				Reserved						
Bit 0				Reserved						

SMBus Table: Output Enable Register

Byt	te 9	Pin#	Name	Control Function	Type	0	1	Default		
Bit 7				Reserved						
Bit 6		-	DIF_3 EN	Output Enable	RW	Disable	Enable	1		
Bit 5		-	DIF_2 EN	Output Enable	RW	Disable	Enable	1		
Bit 4				Reserved						
Bit 3				Reserv	ed			0		
Bit 2				Reserv	ed			0		
Bit 1				Reserved						
Bit 0				Reserv	ed			0		



Stresses above the ratings listed below can cause permanent damage to the 9FGL699. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
3.3V Logic Supply Voltage	VDD				4.6	V	1,2
Input Low Voltage	V_{IL}		GND-0.5			V	1
Input High Voltage	V_{IH}	Except for SMBus interface			$V_{DD}+0.5V$	V	1
Input High Voltage	V _{IHSMB}	SMBus clock and data pins			5.5V	V	1
Storage Temperature	Ts		-65		150	°C	1
Junction Temperature	Tj				125	°C	1
Input ESD protection	ESD prot	Human Body Model	Р			V	1

Guaranteed by design and characterization, not 100% tested in production.

Electrical Characteristics-Input/Supply/Common Output Parameters

 $TA = T_{COM}$; Supply Voltage VDD = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Ambient Operating Temperature	Тсом	Commmercial range	0		70	°C	1
Input Frequency	Fin	X1 pin		25.000		MHz	1
Pin Inductance	L_pin	·			7	nΗ	1
	C _{IN}	Logic Inputs	1.5		5	pF	1
Capacitance	C _{INXTAL}	Crystal inputs			6	pF	1
	C _{OUT}	Output pin capacitance			6	pF	1
Clk Stabilization	T _{STAB}	From V _{DD} Power-Up and after input clock stabilization to 1st clock			1.8	ms	1,2
SS Modulation Frequency	f _{MODIN}	Allowable Frequency (Triangular Modulation)	30	31.500	33	kHz	1
Tfall	t _F	Fall time of control inputs			5	ns	1,2
Trise	t _R	Rise time of control inputs			5	ns	1,2
SMBus Input Low Voltage	V_{ILSMB}				8.0	V	1
SMBus Input High Voltage	V_{IHSMB}		2.1		$V_{\rm DDSMB}$	V	1
SMBus Output Low Voltage	V_{OLSMB}	@ I _{PULLUP}			0.4	V	1
SMBus Sink Current	PULLUP	@ V _{OL}	4			mΑ	1
Nominal Bus Voltage	V_{DDSMB}	3V to 5V +/- 10%	2.7		5.5	V	1
SCLK/SDATA Rise Time	t _{RSMB}	(Max VIL - 0.15) to (Min VIH + 0.15)			1000	ns	1
SCLK/SDATA Fall Time	t _{FSMB}	(Min VIH + 0.15) to (Max VIL - 0.15)			300	ns	1
SMBus Operating Frequency	f _{MAXSMB}	Maximum SMBus operating frequency			100	kHz	1

¹Guaranteed by design and characterization, not 100% tested in production.

² Operation under these conditions is neither implied nor guaranteed.

²Control input must be monotonic from 20% to 80% of input swing.



 $T_A = T_{COM}$: Supply Voltage VDD = 3.3 V +/-5%, See Test Loads for loading conditions

PARAMETER	SYMBOL	CONDITIONS		TYP	MAX	UNITS	NOTES
Slew rate	Trf	Scope averaging on			4	V/ns	1, 2, 3
Slew rate matching	ΔTrf	Slew rate matching, Scope averaging on			20	%	1, 2, 4
Voltage High	VHigh	Statistical measurement on single-ended signal using oscilloscope math function. (Scope averaging	660		850	mV	1
Voltage Low	VLow	using oscilloscope math function. (Scope averaging on)			150		1
Max Voltage	Vmax	Measurement on single ended signal using absolute			1150	mV	1
Min Voltage	Vmin	value. (Scope averaging off)	Р			IIIV	1
Vswing	Vswing	Scope averaging off	300			mV	1, 2
Crossing Voltage (abs)	Vcross_abs	Scope averaging off	300		550	mV	1, 5
Crossing Voltage (var)	Δ-Vcross	Scope averaging off			140	mV	1, 6

¹Guaranteed by design and characterization, not 100% tested in production. $C_L = 2pF$ with $R_S = 33Ω$ for Zo = 50Ω (100Ω differential trace impedance).

Electrical Characteristics-Current Consumption

TA = T_{COM}: Supply Voltage VDD = 3.3 V +/-5%, See Test Loads for loading conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Operating Supply Current	I _{D D3.3}	VDD, All outputs active @100MHz			40	mA	1

¹Guaranteed by design and characterization, not 100% tested in production.

Electrical Characteristics-Output Duty Cycle, Jitter, and Skew Characteristics

 $TA = T_{COM}$; Supply Voltage VDD = 3.3 V +/-5%, See Test Loads for Loading Conditions

99.11, 117							
PARAMETER	SYMBOL	CONDITIONS		TYP	MAX	UNITS	NOTES
Duty Cycle	t _{DC}	Measured differentially, PLL Mode			55	%	1
Skew, Output to Output	t _{sk3}	V _T = 50%			100	ps	1
Jitter, Cycle to cycle	t _{jcyc-cyc}	PLL mode			85	ps	1,3

¹Guaranteed by design and characterization, not 100% tested in production.

² Measured from differential waveform

³ Slew rate is measured through the Vswing voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

⁴ Matching applies to rising edge rate of Clock / falling edge rate of Clock#. It is measured in a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope uses for the edge rate calculations.

⁵ Vcross is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

⁶ The total variation of all Vcross measurements in any particular system. Note that this is a subset of V_cross_min/max (V_cross absolute) allowed. The intent is to limit Vcross induced modulation by setting V_cross_delta to be smaller than V_cross abs.

³ Measured from differential waveform

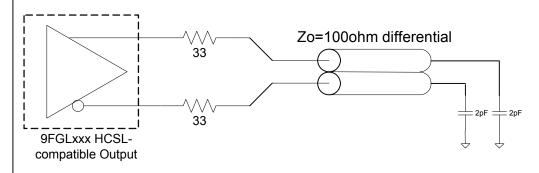


TA = T_{COM;} Supply Voltage VDD = 3.3 V +/-5%, See Test Loads for loading conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	Notes
	t _{iphPCleG1}	PCle Gen 1			86	ps (p-p)	1,2,3,6
	t _{ip hPCleG2}	PCIe Gen 2 Lo Band				ps	1,2,6
Phase Jitter, PCI Express		10kHz < f < 1.5MHz			3	(ms)	1,2,0
		PCIe Gen 2 High Band			3.1	ps	106
		1.5 MHz < f < N yquist (50 MHz)			3.1	(ms)	1,2,6

¹Guaranteed by design and characterization, not 100% tested in production.

Low-Power Differential Output Test Load



9FGL699

² See http://www.pcisig.com for complete specs

³ Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

⁶ Applies to all differential outputs



Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Thermal Resistance Junction to	θ_{JA}	Still air		34		°C/W
Ambient	θ_{JA}	1 m/s air flow		29		°C/W
	θ_{JA}	3 m/s air flow		27		°C/W
Thermal Resistance Junction to Case	θЈС			32		°C/W

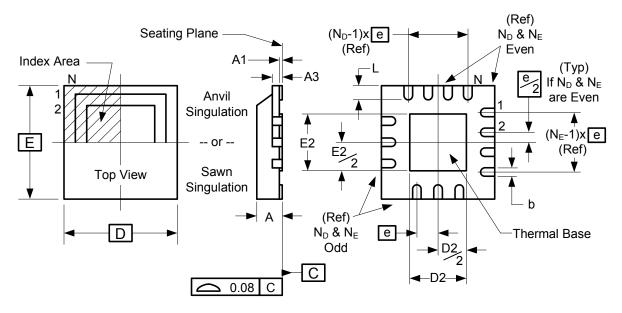
Marking Diagram



Notes:

- 1. 'LOT' is the lot number.
- 2. 'COO' is country of origin.
- 3. YYWW is the last two digits of the year and week that the part was assembled.
- 4. "L" denotes RoHS compliant package.





	Millim	eters	
Symbol	Min	Max	
Α	0.8	1.0	
A1	0	0.05	
A3	0.20 Reference		
b	0.18	0.3	
е	e 0.50 BASI		
D x E BASIC	5.00 >	5.00	
D2 MIN./MAX.	3.00	3.30	
E2 MIN./MAX.	3.00	3.30	
L MIN./MAX.	0.30	0.50	
N	3	2	
N_D	8		
N _E	8		

Ordering Information

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
9FGL699AKLF	see page 11	Trays	32-pin MLF	0 to +70° C
9FGL699AKLFT		Tape and Reel	32-pin MLF	0 to +70° C

[&]quot;LF" suffix to the part number are the Pb-Free configuration, RoHS compliant.

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[&]quot;A" is the device revision designator (will not correlate with the datasheet revision).



Rev.	Issue Date	WHO	Description	Page #
Α	04/05/12	AT	Released to Final	
В	01/31/13	1 A I	Updated Cycle-to-cycle jitter max spec from 125ps to 85ps per latest characterization data.	9



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